



# H21A1 H21A2 H21A3 Phototransistor Optical Interrupter Switch

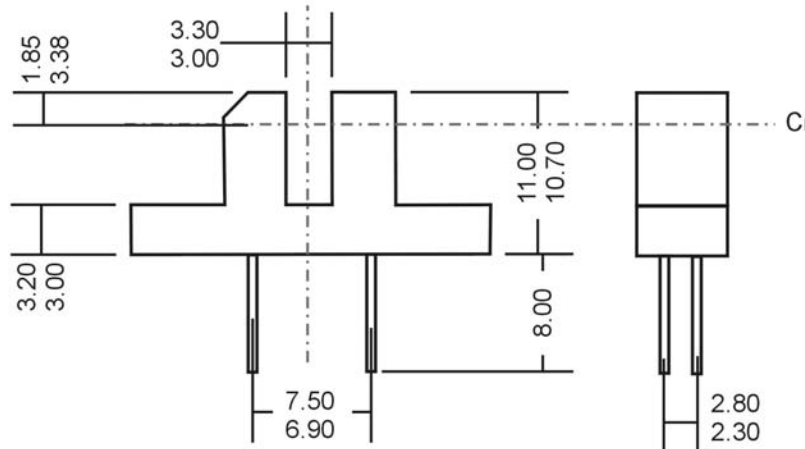
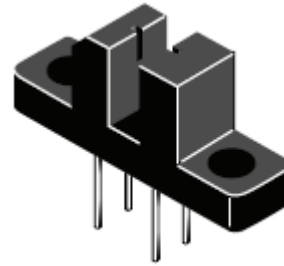
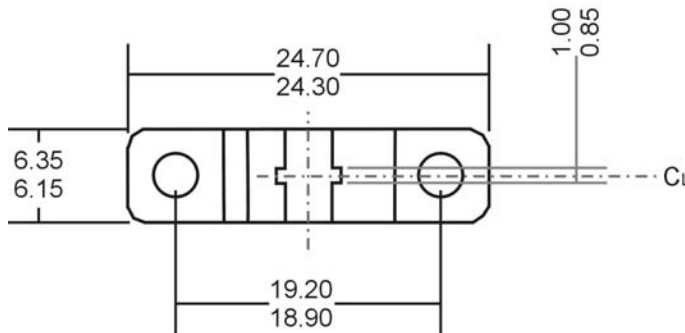
## Features

- No Contact Sensing
- 1mm Aperture
- High  $I_{C(ON)}$
- PCB mount
- Transistor output

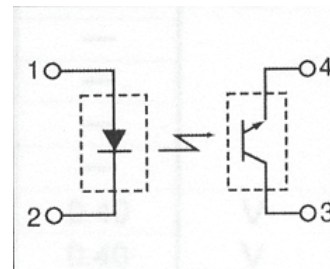
## Description

The H21AX products consist of an infrared light emitting diode coupled to an NPN silicon phototransistor packaged in an injection molded housing. The package is designed to optimize the mechanical resolution, coupling efficiency, ambient light rejection, and reliability. Inserting/removing an opaque material into the gap when the LED is operating, switches the transistor on/off.

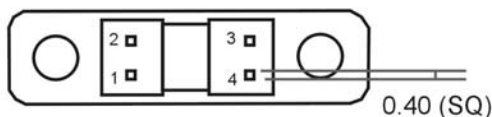
## Package Dimensions



## Schematic



Pin 1 Anode  
Pin 2 Cathode  
Pin 3 Collector  
Pin 4 Emitter



## Notes

1. Dimensions for all drawings are in millimeters.
2. Tolerance of +/- 0.25 on all non nominal dimensions unless otherwise specified

**Absolute Maximum Ratings** ( $T_A = 25^\circ\text{C}$  unless otherwise specified)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In Addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating	Units
$T_{OPR}$	Operating Temperature	-55 to +100	$^\circ\text{C}$
$T_{STG}$	Storage Temperature	-55 to +100	$^\circ\text{C}$
$T_{SOL-I}$	Soldering Temperature (Iron) <sup>(2,3,4,5)</sup>	240 for 5 sec	$^\circ\text{C}$
$T_{SOL-F}$	Soldering Temperature (Flow) <sup>(2,3,5)</sup>	260 for 10 sec	$^\circ\text{C}$
<b>Emitter</b>			
$I_F$	Continuous Forward Current <sup>(6)</sup>	50	mA
$V_R$	Reverse Voltage	6	V
$P_D$	Power Dissipation <sup>(1)</sup>	100	mW
<b>Sensor</b>			
$V_{CEO}$	Collector-Emitter Voltage	30	V
$V_{ECO}$	Emitter-Collector Voltage	4.5	V
$I_C$	Collector Current	20	mA
$P_D$	Power Dissipation <sup>(1)</sup>	150	mW

**Notes:**

- Derate power dissipation linearly, on Sensor, 1.33 mW/ $^\circ\text{C}$  above 25 $^\circ\text{C}$ .
- RMA Flux is recommended.
- Methanol or isopropyl alcohols are recommended as cleaning agents.
- Soldering iron tip 1.6mm from housing.
- As long as leads are not under stress or spring tension

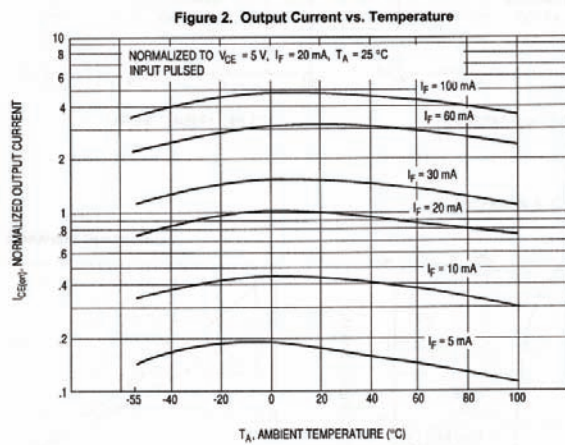
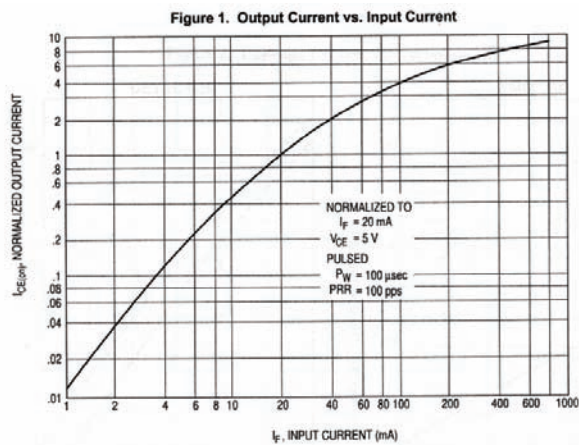
**Electrical/Optical Characteristics** ( $T_A = 25^\circ\text{C}$ )

<b>EMITTER</b>						
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_F$	Forward Voltage	$I_F = 50\text{mA}$			1.7	V
$V_R$	Reverse Breakdown Voltage	$I_R = 10\mu\text{A}$	6			V
$I_R$	Reverse Leakage Current	$V_R = 3\text{V}$			100	nA
<b>SENSOR</b>						
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$BV_{CEO}$	Collector-Emitter Breakdown Voltage	$I_C = 1\text{mA}, E_e = 0$	30			V
$BV_{ECO}$	Emitter-Collector Breakdown Voltage	$I_{EC} = 100\mu\text{A}, E_e = 0$	6			V
$I_{CEO}$	Collector-Emitter Leakage	$V_{CE} = 10\text{V}, I_F = 0$			100	nA

**Electrical/Optical Characteristics Cont. ( $T_A = 25^{\circ}C$ )**

COUPLED						
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$t_{(ON)}$	Turn-on Time	$I_F = 30mA, V_{CC} = 5V, R_L = 2.5k\Omega$		8		$\mu s$
$t_{(OFF)}$	Turn-Off Time	$I_F = 30mA, V_{CC} = 5V, R_L = 2.5k\Omega$		50		$\mu s$
ON-STATE COLLECTOR CURRENT						
Symbol	Device	Test Conditions	Min.	Typ.	Max.	Units
$I_C (ON)$	H21A1	$I_F = 5mA, V_{CE} = 5V$	0.15			mA
	H21A2		0.30			
	H21A3		0.60			
	H21A1	$I_F = 20mA, V_{CE} = 5V$	1.0			mA
	H21A2		2.0			
	H21A3		4.0			
	H21A1	$I_F = 30mA, V_{CE} = 5V$	1.9			mA
	H21A2		3			
	H21A3		5.5			
COLLECTOR CURRENT SATURATION VOLTAGE						
Symbol	Device	Test Conditions	Min.	Typ.	Max.	Units
$V_{CE (SAT)}$	H21A1, H21A2, H21A3,	$I_C = 1.8mA, I_F = 20mA$			0.40	V
					0.40	V

**Typical Performance Characteristics**



## Typical Performance Characteristics

Figure 3.  $V_{CE(SAT)}$  vs. Temperature

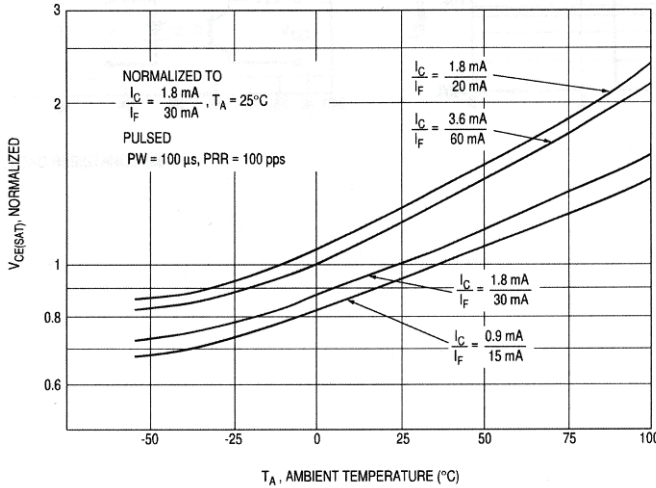


Figure 5. Switching Speed vs.  $R_L$

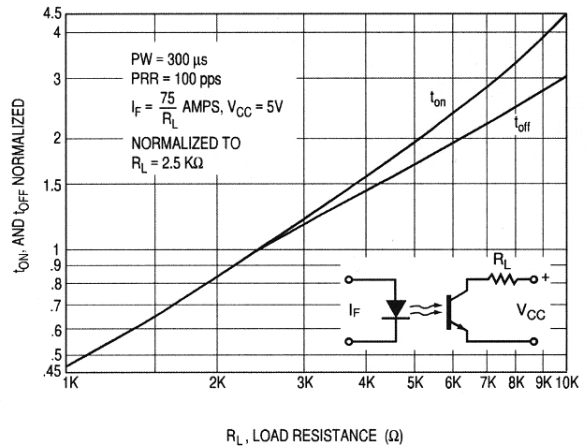


Figure 4. Leakage Current vs. Temperature

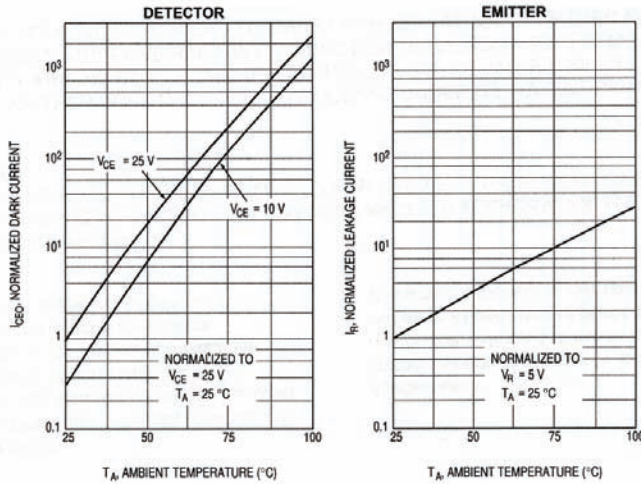
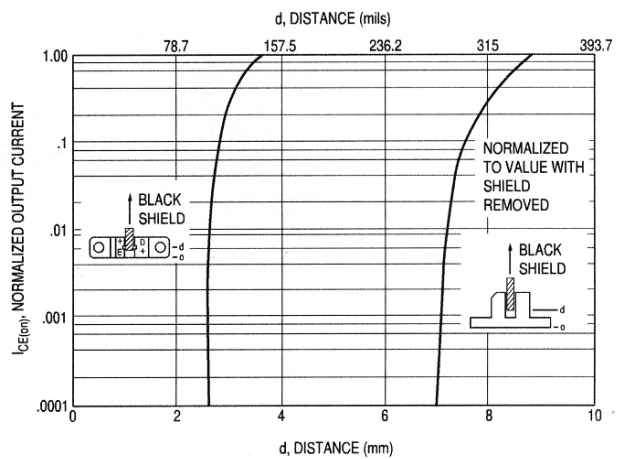


Figure 6. Output Current vs. Distance



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